# **Electrical Datasheet\***

**GA01PNS80-CAL** 

# Silicon Carbide PiN Diode Chip

#### **Features**

- 8 kV blocking
- 250 °C operating temperature
- · Fast turn off characteristics
- Soft reverse recovery characteristics
- · Ultra-Fast high temperature switching



### **Advantages**

- Industry's lowest conduction losses
- Reduced stacking
- · Reduced system complexity/Increased reliability

### **Applications**

- Voltage Multiplier
- Ignition/Trigger Circuits
- Oil/Downhole
- Lighting
- Defense

### Maximum Ratings at $T_j$ = 250 °C, unless otherwise specified

Parameter	Symbol	Conditions	Values	Unit
Repetitive peak reverse voltage	$V_{RRM}$		8	kV
Continuous forward current	l <sub>F</sub>	T <sub>C</sub> ≤ 150 °C	2	Α
RMS forward current	I <sub>F(RMS)</sub>	T <sub>C</sub> ≤ 150 °C	1	Α
Operating and storage temperature	$T_{j}$ , $T_{stg}$		-55 to 250	°C

#### Electrical Characteristics at T<sub>j</sub> = 250 °C, unless otherwise specified

Dougranton	Oala al	Conditions -		Values		I I m l 4	
Parameter	Symbol			min.	typ.	max.	Unit
Diode forward voltage	$V_{F}$	$I_F = 2 A, T_j = 1$	25 °C		4.6	4.8	V
		I <sub>F</sub> = 2 A, T <sub>j</sub> = 225 °C			3.9	4.5	v
Reverse current	$I_{R}$	V <sub>R</sub> = 8 kV, T <sub>j</sub> = 25 °C		0.1	3	^	
		$V_R = 8 \text{ kV}, T_j =$	175 °C			50	μΑ
Total reverse recovery charge	Q <sub>rr</sub>	I <sub>F</sub> ≤ I <sub>F,MAX</sub>	V <sub>R</sub> = 1000 V I <sub>F</sub> = 1.5 A		558		nC
Switching time	t <sub>s</sub>	$dI_F/dt = 70 \text{ A/}\mu\text{s}$ $T_j = 225 \text{ °C}$	V <sub>R</sub> = 1000 V I <sub>F</sub> = 1.5 A		< 236		ns
		$V_R = 1 \text{ V}, f = 1 \text{ MHz}, T_j = 25 \text{ °C}$ $V_R = 400 \text{ V}, f = 1 \text{ MHz}, T_j = 25 \text{ °C}$		20		pF	
Total capacitance	С			5			
		V <sub>R</sub> = 1000 V, f = 1 MH	Hz, T <sub>j</sub> = 25 °C		4		-
Total capacitive charge	$Q_{C}$	V <sub>R</sub> = 1000 V, f = 1 MH	Hz, T <sub>j</sub> = 25 °C		5.34		nC

<sup>\*</sup>For chip size and metallization, please refer to the mechanical datasheet (must have a non-disclosure agreement with GeneSiC Semiconductor).

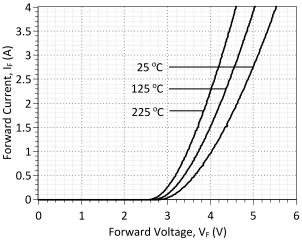


Figure 1: Typical Forward Characteristics

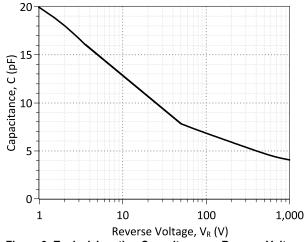


Figure 3: Typical Junction Capacitance vs Reverse Voltage Characteristics

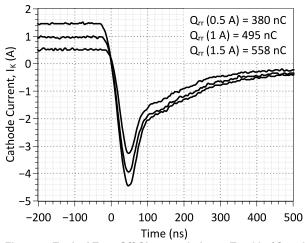


Figure 5: Typical Turn Off Characteristics at  $T_j$  = 225 °C and  $V_R$  = 1000 V

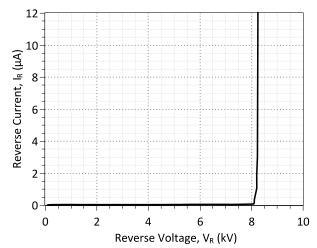


Figure 2: Typical Reverse Characteristics

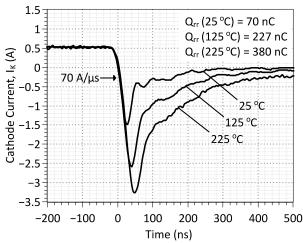


Figure 4: Typical Turn Off Characteristics at  $I_{\text{k}}$  = 0.5 A and  $V_{\text{R}}$  = 1000 V

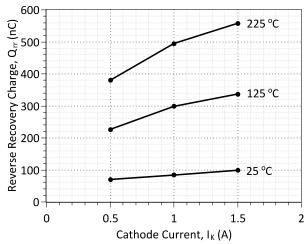


Figure 6: Reverse Recovery Charge vs Cathode Current

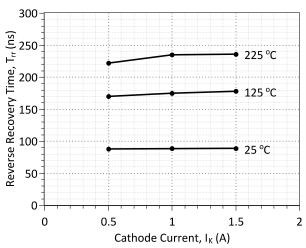


Figure 7: Reverse Recovery Time vs Cathode Current

Revision History						
Date	Revision	Comments	Supersedes			
2013/02/18	0	Initial release				

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